

MICROELECTRONIC SPRING CONTACT REPAIR METHOD

ABSTRACT OF THE DISCLOSURE

A method for replacing a microelectronic spring contact bonded to a terminal of a substrate is disclosed. The method comprises removing the microelectronic spring contact from the terminal, such as by cutting the microelectronic spring contact in two adjacent to the terminal. Then, a bonding material, such as a solder paste, is applied to the terminal and a replacement spring contact is positioned on the bonding material. The bonding material is then cured to fix the replacement spring contact in place. The replacement spring contact includes a base configured to fit on or over any protruding material left on the terminal, and at least one resilient cantilever arm extending from the base. In an embodiment of the invention, the base comprises at least two legs extending from the base in a direction opposite to the cantilever arm. In an alternative embodiment, the base of the replacement spring contact has a flat bottom, or one or more recesses to receive protrusions on the terminal. The replacement spring contact is positioned with its base opposite to the terminal and the resilient cantilever arm extending away from the substrate. A method for forming a suitable replacement spring contact is also disclosed.